

# SN54107, SN54LS107A, SN74107, SN74LS107A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

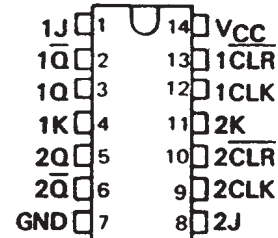
## description

The '107 contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '107 is a positive pulse-triggered flip-flop. The J-K input data is loaded into the master while the clock is high and transferred to the slave and the outputs on the high-to-low clock transition. For these devices the J and K inputs must be stable while the clock is high.

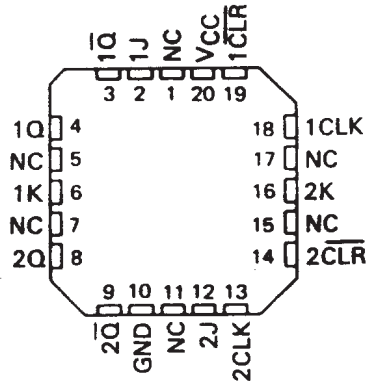
The 'LS107A contain two independent negative-edge-triggered flip-flops. The J and K inputs must be stable prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the  $\bar{Q}$  output high.

The SN54107 and the SN54LS107A are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74107 and the SN74LS107A are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54107, SN54LS107A . . . J PACKAGE  
SN74107 . . . N PACKAGE  
SN74LS107A . . . D OR N PACKAGE  
(TOP VIEW)



SN54LS107A . . . FK PACKAGE  
(TOP VIEW)



NC - No internal connection

'107  
FUNCTION TABLE

INPUTS				OUTPUTS	
$\overline{\text{CLR}}$	CLK	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H	$\downarrow$	L	L	$Q_0$	$\bar{Q}_0$
H	$\downarrow$	H	L	H	L
H	$\downarrow$	L	H	L	H
H	$\downarrow$	H	H	TOGGLE	
H	H	X	X	$Q_0$	$\bar{Q}_0$

'LS107A  
FUNCTION TABLE

INPUTS				OUTPUTS	
$\overline{\text{CLR}}$	CLK	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H	$\downarrow$	L	L	$Q_0$	$\bar{Q}_0$
H	$\downarrow$	H	L	H	L
H	$\downarrow$	L	H	L	H
H	$\downarrow$	H	H	TOGGLE	
H	H	X	X	$Q_0$	$\bar{Q}_0$

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

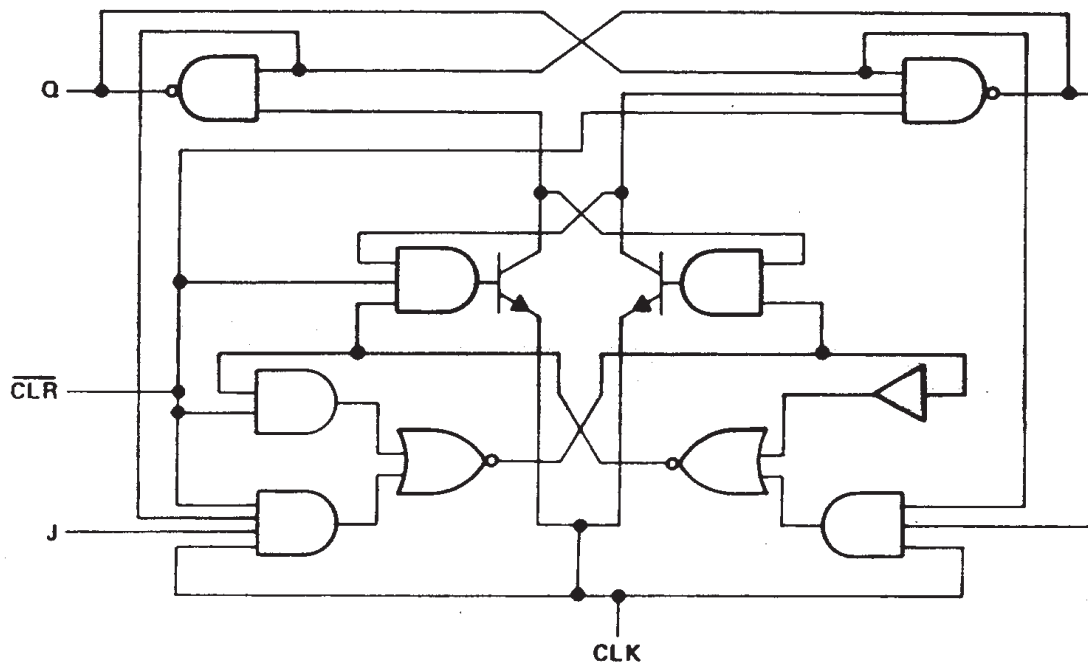


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

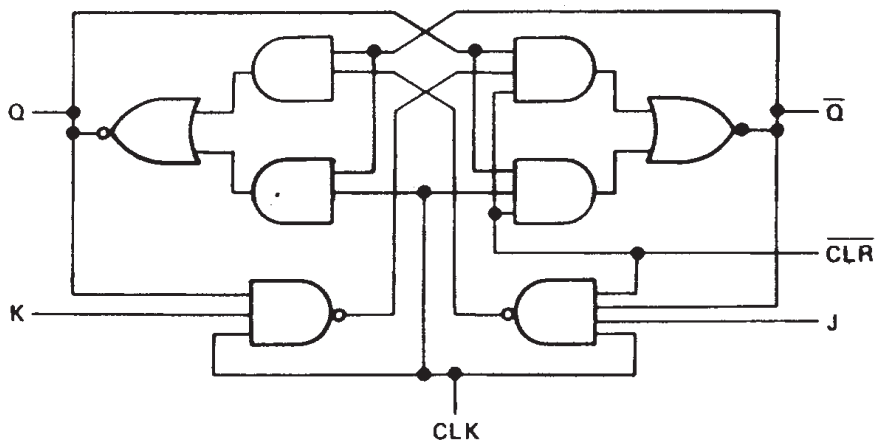
Copyright © 1988, Texas Instruments Incorporated

SN54107, SN54LS107A,  
 SN74107, SN74LS107A  
 DUAL J-K FLIP-FLOPS WITH CLEAR  
 SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

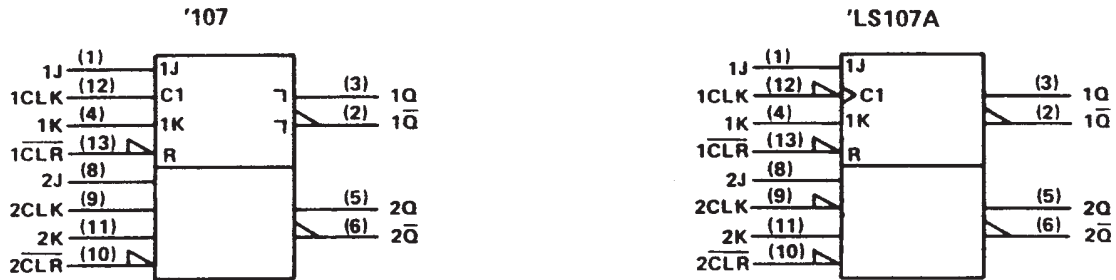
logic diagrams (positive logic)



'LS107A

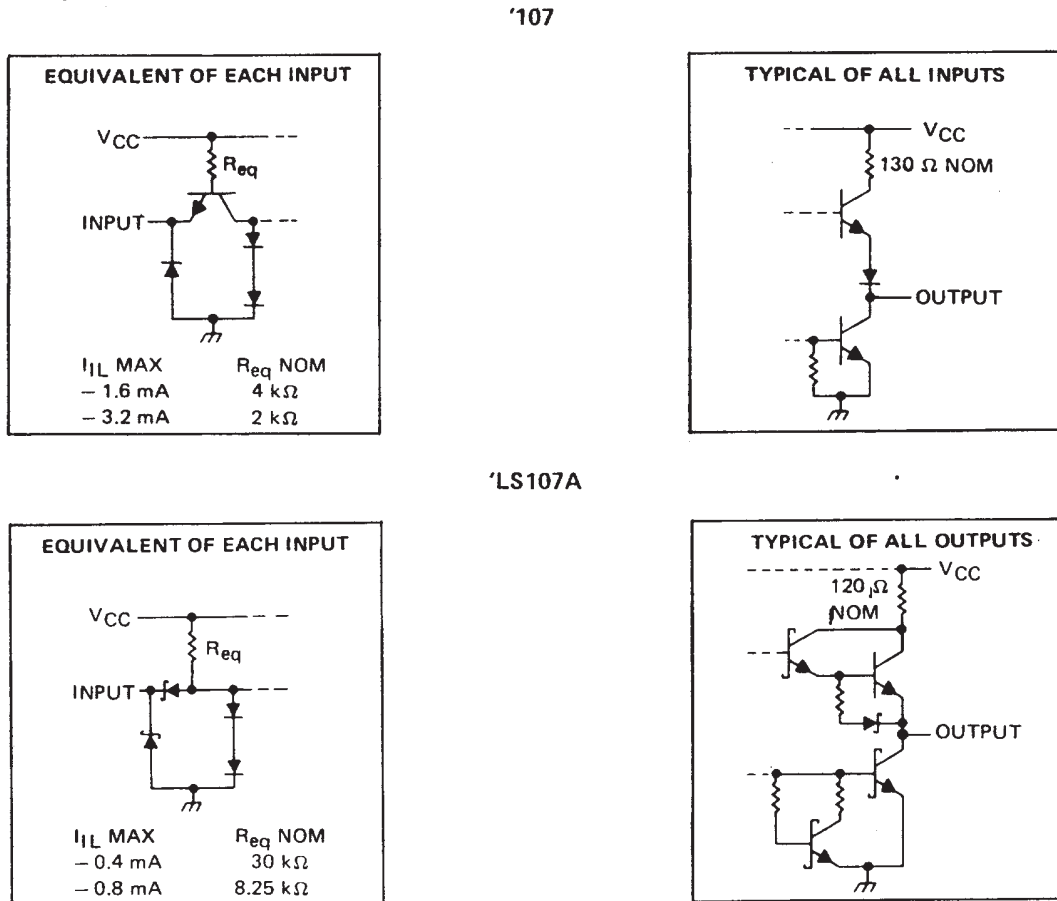


logic symbols †



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.  
Pin numbers shown are for D, J, and N packages.

schematic of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage: '107	5.5 V
'LS107A	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

# SN54107, SN74107 DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

		SN54107			SN74107			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.8			0.8	V
$I_{OH}$	High-level output current			-0.4			-0.4	mA
$I_{OL}$	Low-level output current			16			16	mA
$t_w$	Pulse duration	CLK high		20	20		ns	
		CLK low		47	47			
		CLR low		25	25			
$t_{su}$	Input setup time before CLK†	0			0			ns
$t_h$	Input hold time-data after CLK†	0			0			ns
$T_A$	Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54107			SN74107			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$	$V_{CC} = \text{MIN}$ , $I_I = -12 \text{ mA}$			-1.5			-1.5	V
$V_{OH}$	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OH} = -0.4 \text{ mA}$	2.4	3.4		2.4	3.4		V
$V_{OL}$	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OL} = 16 \text{ mA}$		0.2	0.4		0.2	0.4	V
$I_I$	$V_{CC} = \text{MAX}$ , $V_I = 5.5 \text{ V}$			1			1	mA
$I_{IH}$	J or K			40			40	$\mu\text{A}$
	All other			80			80	
$I_{IL}$	J or K			-1.6			-1.6	mA
	All other			-3.2			-3.2	
$I_{OS}§$	$V_{CC} = \text{MAX}$	-20		-57	-18		-57	mA
$I_{CC}¶$	$V_{CC} = \text{MAX}$ , See Note 2		10	20		10	20	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ \text{C}$ .

§Not more than one output should be shorted at a time.

¶Average per flip-flop.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\bar{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^\circ \text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{max}$			$R_L = 400 \Omega$ , $C_L = 15 \text{ pF}$	15	20		MHz
$t_{PLH}$	CLR	$\bar{Q}$			16	25	ns
$t_{PHL}$		Q			25	40	ns
$t_{PLH}$	CLK	Q or $\bar{Q}$			16	25	ns
$t_{PHL}$						25	40

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# SN54LS107A, SN74LS107A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

		SN54LS107A			SN74LS107A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage	0.7			0.8			V
I <sub>OH</sub>	High-level output current	-0.4			-0.4			mA
I <sub>OL</sub>	Low-level output current	4			8			mA
f <sub>clock</sub>	Clock frequency	0	30		0	30		MHz
t <sub>w</sub>	Pulse duration	CLK high		20		20		ns
		CLR low		25		25		
t <sub>su</sub>	Setup time before CLK ↓	data high or low		20		20		ns
		CLR inactive		25		25		
t <sub>h</sub>	Hold time-data after CLK ↓	0			0			ns
T <sub>A</sub>	Operating free-air temperature	-55	125		0	70		°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS107A		SN74LS107A		UNIT
		MIN	TYP ‡	MAX	MIN	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA	-1.5		-1.5		V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX, I <sub>OH</sub> = -0.4 mA	2.5	3.4	2.7	3.4	V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 4 mA	0.25	0.4	0.25	0.4	V
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 8 mA			0.35	0.5	
I <sub>I</sub>	J or K	0.1		0.1		mA
	CLR	0.3		0.3		
	CLK	0.4		0.4		
I <sub>IH</sub>	J or K	20		20		μA
	CLR	60		60		
	CLK	80		80		
I <sub>IL</sub>	J or K	-0.4		-0.4		mA
	CLR or CLK	-0.8		-0.8		
I <sub>OS</sub> §	V <sub>CC</sub> = MAX, See Note 4	-20	-100	-20	-100	mA
I <sub>CC</sub> (Total)	V <sub>CC</sub> = MAX, See Note 2	4	6	4	6	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and  $\bar{Q}$ , outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V<sub>O</sub> = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>			R <sub>L</sub> = 2 kΩ, C <sub>L</sub> = 15 pF	30	45		MHz
t <sub>PLH</sub>	$\bar{CLR}$ or CLK	Q or $\bar{Q}$		15	20		ns
t <sub>PHL</sub>				15	20		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00203BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	<a href="#">Samples</a>
M38510/00203BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	<a href="#">Samples</a>
M38510/00203BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00203BCA	<a href="#">Samples</a>
SN54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54107J	<a href="#">Samples</a>
SN54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54107J	<a href="#">Samples</a>
SN74LS107AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS107A	<a href="#">Samples</a>
SN74LS107AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS107A	<a href="#">Samples</a>
SN74LS107AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS107AN	<a href="#">Samples</a>
SN74LS107AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS107AN	<a href="#">Samples</a>
SN74LS107ANSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS107A	<a href="#">Samples</a>
SN74LS107ANSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS107A	<a href="#">Samples</a>
SNJ54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54107J	<a href="#">Samples</a>
SNJ54107J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54107J	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS107ANSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS107ANSR	SOP	NS	14	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LS107AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS107AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS107AN	N	PDIP	14	25	506	13.97	11230	4.32



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

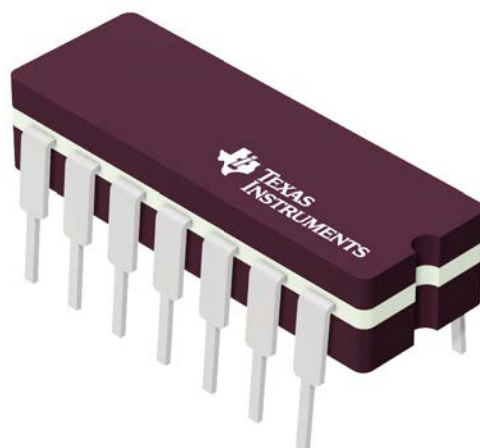
**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2024, Texas Instruments Incorporated